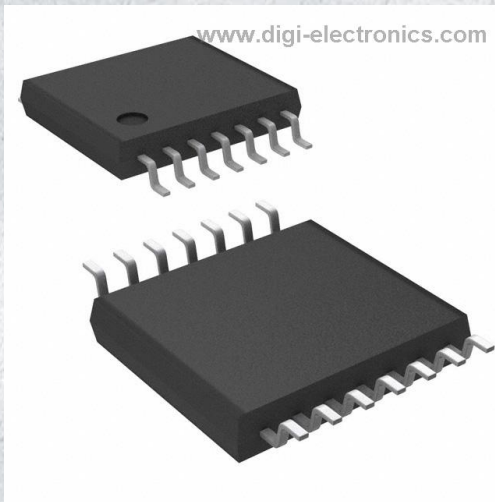


74LVX08MTCX Datasheet



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	74LVX08MTCX-DG
Manufacturer	onsemi
Manufacturer Product Number	74LVX08MTCX
Description	IC GATE AND 4CH 2-INP 14TSSOP
Detailed Description	AND Gate IC 4 Channel 14-TSSOP



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

74LVX08MTCX

Series:

74LVX

Logic Type:

AND Gate

Number of Inputs:

2

Voltage - Supply:

2V ~ 3.6V

Current - Output High, Low:

4mA, 4mA

Input Logic Level - High:

1.5V ~ 2.4V

Operating Temperature:

-40°C ~ 85°C

Supplier Device Package:

14-TSSOP

Base Product Number:

74LVX08

Manufacturer:

onsemi

Product Status:

Active

Number of Circuits:

4

Features:

-

Current - Quiescent (Max):

2 μ A

Input Logic Level - Low:

0.5V ~ 0.8V

Max Propagation Delay @ V, Max CL:

10.6ns @ 3.3V, 50pF

Mounting Type:

Surface Mount

Package / Case:

14-TSSOP (0.173", 4.40mm Width)

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8542.39.0001

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

Low Voltage Quad 2-Input AND Gate

74LVX08

Description

The LVX08 contains four 2-input AND gates. The inputs tolerate voltages up to 6.5 V allowing the interface of 5 V systems to 3 V systems.

Features

- Input Voltage Level Translation from 5 V to 3 V
- Ideal for Low Power/Low Noise 3.3 V Applications
- Guaranteed Simultaneous Switching Noise Level and Dynamic Threshold Performance

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Ratings	Unit	
V_{CC}	Supply Voltage	-0.5 to 6.5	V	
I_{IK}	DC Input Diode Current, $V_I = -0.5$ V	-20	mA	
V_I	DC Input Voltage	-0.5 to 6.5	V	
I_{OK}	DC Output Diode Current	$V_O = -0.5$ V	-20	mA
		$V_O = V_{CC} + 0.5$ V	+20	
V_O	DC Output Voltage	-0.5 to $V_{CC} + 0.5$	V	
I_O	DC Output Source or Sink Current	± 25	mA	
I_{CC} or I_{GND}	DC V_{CC} or Ground Current	± 50	mA	
T_{STG}	Storage Temperature	-65 to 150	$^{\circ}$ C	
P_D	Power Dissipation	SOIC	1077	mW
		TSSOP	833	
T_L	Lead Temperature (Soldering, 10 Second)	240	$^{\circ}$ C	

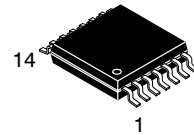
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS (Note 1)

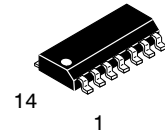
Symbol	Parameter	Min	Max	Unit
V_{CC}	Supply Voltage	2.0	3.6	V
V_I	Input Voltage	0	5.5	V
V_O	Output Voltage	0	V_{CC}	V
T_A	Operating Temperature	-40	+85	$^{\circ}$ C
$\Delta t / \Delta V$	Input Rise and Fall Time	0	100	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

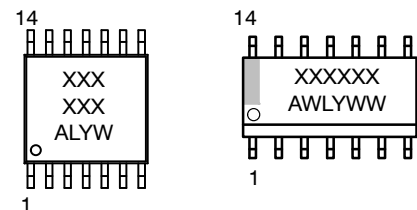


TSSOP-14, WB
CASE 948G



SOIC14
CASE 751EF

MARKING DIAGRAM



XXX = Specific Device Code
 A = Assembly Location
 WL, L = Wafer Lot
 Y = Year
 WW, W = Work Week

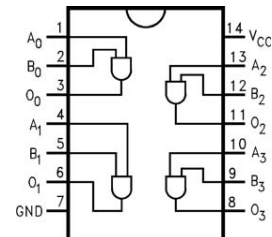


Figure 1. Connection Diagram

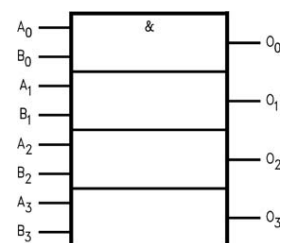


Figure 2. Logic Symbol

PIN DESCRIPTION

PIN NAMES	DESCRIPTION
A_n, B_n	Inputs
O_n	Outputs

ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

74LVX08

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V _{CC}	Conditions	T _A = 25°C			T _A = -40°C to +85°C			Unit
				Min	Typ	Max	Min	Typ	Max	
V _{IH}	HIGH Level Input Voltage	2.0		1.5	-	-	1.5	-	-	V
		3.0		2.0	-	-	2.0	-	-	
		3.6		2.4	-	-	2.4	-	-	
V _{IL}	LOW Level Input Voltage	2.0		-	-	0.5	-	-	0.5	V
		3.0		-	-	0.8	-	-	0.8	
		3.6		-	-	0.8	-	-	0.8	
V _{OH}	HIGH Level Output Voltage	2.0	V _{IN} = V _{IL} or V _{IH} , I _{OH} = -50 μA	1.9	2.0	-	1.9	-	-	V
		3.0	V _{IN} = V _{IL} or V _{IH} , I _{OH} = -50 μA	2.9	3.0	-	2.9	-	-	
			V _{IN} = V _{IL} or V _{IH} , I _{OH} = -4 mA	2.58	-	-	2.48	-	-	
V _{OL}	LOW Level Output Voltage	2.0	V _{IN} = V _{IL} or V _{IH} , I _{OL} = -50 μA	-	0.0	0.1	-	-	0.1	V
		3.0	V _{IN} = V _{IL} or V _{IH} , I _{OL} = -50 μA	-	0.0	0.1	-	-	0.1	
			V _{IN} = V _{IL} or V _{IH} , I _{OL} = -4 mA	-	-	0.36	-	-	0.44	
I _{IN}	Input Leakage Current	3.6	V _{IN} = 5.5 V or GND	-	-	±0.1	-	-	±1.0	μA
I _{CC}	Quiescent Supply Current	3.6	V _{IN} = V _{CC} or GND	-	-	2.0	-	-	20.0	μA

NOISE CHARACTERISTICS (Note 2)

Symbol	Parameter	V _{CC} (V)	C _L (pF)	T _A = -40°C		Unit
				Typ	Limit	
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3	50	0.3	0.8	V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3	50	-0.3	-0.5	V
V _{IHD}	Minimum HIGH Level Dynamic Input Voltage	3.3	50	-	2.0	V
V _{ILD}	Maximum LOW Level Dynamic Input Voltage	3.3	50	-	0.8	V

2. Input t_r = t_f = 3 ns

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V _{CC}	Conditions	T _A = 25°C			T _A = -40°C to +85°C			Unit
				Min	Typ	Max	Min	Typ	Max	
t _{PLH} , t _{PHL}	Propagation Delay Time	2.7	C _L = 15 pF	-	6.3	11.4	1.0	-	13.5	ns
			C _L = 50 pF	-	8.8	14.9	1.0	-	17.0	
		3.3 ± 0.3	C _L = 15 pF	-	4.8	7.1	1.0	-	8.5	
			C _L = 50 pF	-	7.3	10.6	1.0	-	12.0	
t _{OSLH} , t _{OSSL}	Output to Output Skew (Note 3)	2.7	C _L = 50 pF	-	-	1.5	-	-	1.5	ns
		3.3		-	-	1.5	-	-	1.5	

3. Parameter guaranteed by design t_{OSLH} = |t_{PLHm} - t_{PLHn}|, t_{OSSL} = |t_{PHLm} - t_{PHLn}|.

74LVX08**CAPACITANCE**

Symbol	Parameter	T _A = 25°C			T _A = -40°C to +85°C			Unit
		Min	Typ	Max	Min	Typ	Max	
C _{IN}	Input Capacitance	-	4	10	-	-	10	pF
C _{PD}	Power Dissipation Capacitance (Note 4)	-	18	-	-	-	-	pF

4. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

$$\text{Average operating current can be obtained by the equation: } I_{CC(opr.)} = \frac{C_{PD} \times V_{CC} \times f_{IN} \times I_{CC}}{4 \text{ (per Gate)}}$$

ORDERING INFORMATION

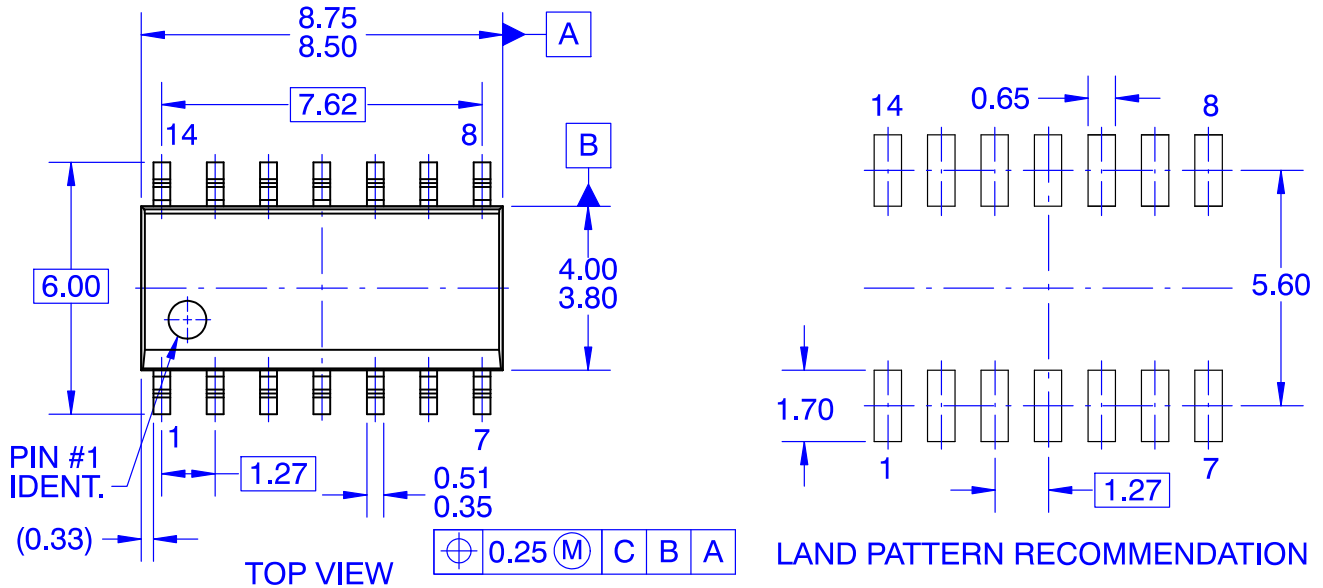
Product Number	Package	Marking	Shipping [†]
74LVX08MTCX	TSSOP-14 WB (Pb-Free/Halide Free)	LVX 08	2500 / Tape and Reel
74LVX08MX	SOIC14 (Pb-Free/Halide Free)	LVX08	2500 / Tape and Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

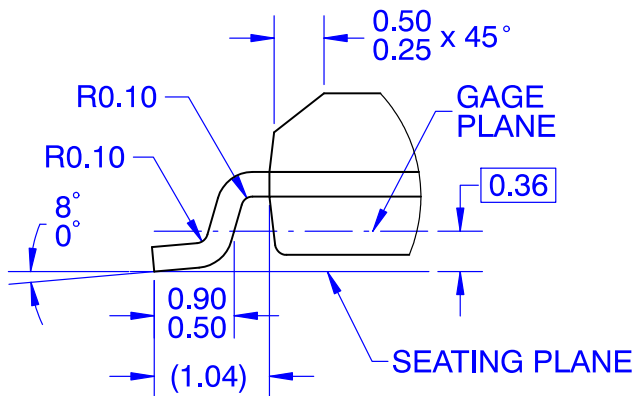
SOIC14
CASE 751EF
ISSUE O

DATE 30 SEP 2016



NOTES:

- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- D. LAND PATTERN STANDARD: SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009



DETAIL A
SCALE 16 : 1

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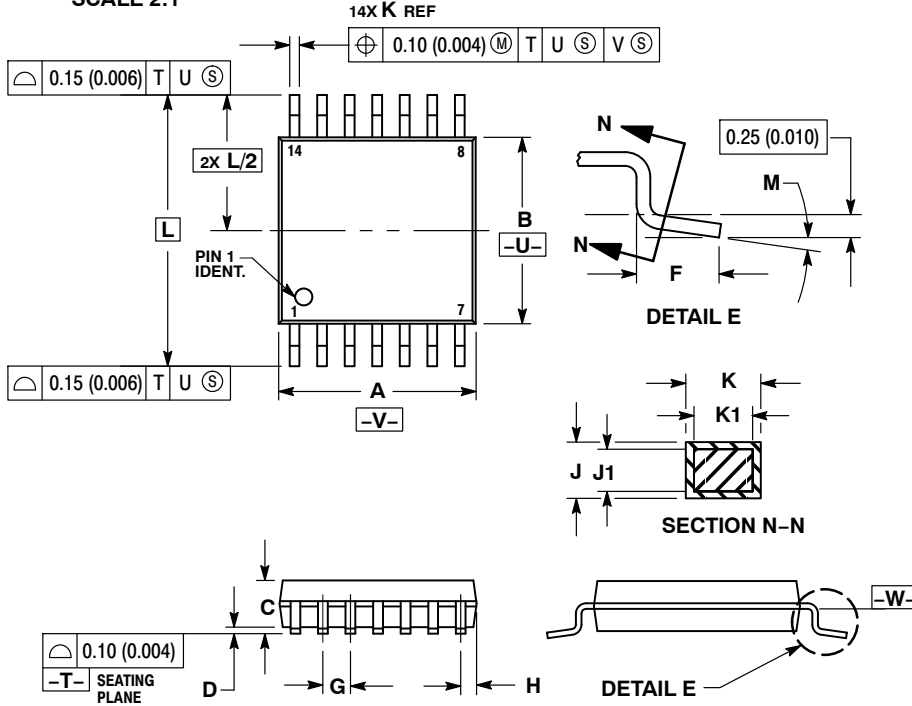
**MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS**



**TSSOP-14 WB
CASE 948G
ISSUE C**

DATE 17 FEB 2016

SCALE 2:1

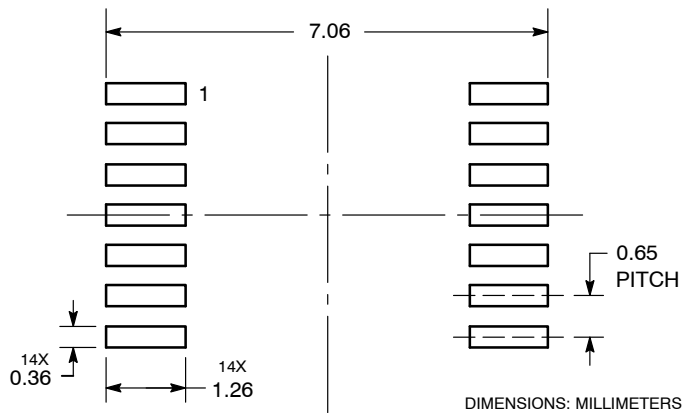


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

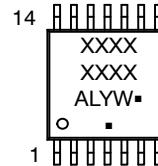
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**RECOMMENDED
SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC
MARKING DIAGRAM***



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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